

04-02-2004

## FORM COVER SHEET Patents Only

To the Director  
Please record th

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ce:  
of copy thereof.

Attorney Dkt. No.: 035576/276102

## 1. Name of conveying party(ies):

Fujio YAGIHASHI  
Yoshitaka HAMADA  
Hideo NAKAGAWA  
Masaru SASAGO

Additional name(s) of conveying party(ies) attached?

Yes ☐ No ☒

## 2. Name and address of receiving party(ies):

Shin-Etsu Chemical Co., Ltd.  
6-1, Otemachi 2-chome,  
Chiyoda-ku, Tokyo, JAPANMatsushita Electric Industrial Co., Ltd.  
1006, Oaza Kadoma, Kadoma-shi  
Osaka 571-8501 JAPAN22859 U.S. PTO  
10/810360

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## 3. Nature of conveyance:

- ☒
- Assignment
- 
- ☐
- Merger
- 
- ☐
- Security Agreement
- 
- ☐
- Change of Name
- 
- ☐
- Other: .

Execution Date: 03/05/04,

Additional name(s) &amp; address(es) attached? No

## 4. Application No. \_\_\_\_\_

Patent No. \_\_\_\_\_

If this document is being filed together with a new application, the execution date of the application is: \_\_\_\_\_

Additional numbers attached? Yes ☐ No ☒

10810360

## 5. Name and address of party to whom correspondence concerning document should be mailed:

ALSTON & BIRD LLP  
Bank of America Plaza  
101 South Tryon Street, Suite 4000  
Charlotte, NC 28280-4000

## 6. Total number of applications and patents involved:

1

03/30/2004 KBETEMA1 00000025 10810360

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40.00 DP

## 7. Total fee (37 CFR 3.41) \$40.00

- ☒
- Enclosed
- 
- ☐
- Authorized to be charged to deposit account

## 8. Deposit account number: 16-0605

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9. Statement and signature: *To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Name of Person Signing: Melissa B. Pendleton

March 26, 2004

Date

Reg. No. 35,459

Total number of pages including cover sheet, attachments, and document: 3

USPTO Fax Number for Corrective Assignments (703) 306-5995

PATENT  
REEL: 015158 FRAME: 0162

# ASSIGNMENT

WHEREAS: Fujio YAGIHASHI and Yoshitaka HAMADA of c/o New Functional Materials Research Center, SHIN-ETSU CHEMICAL CO., LTD., 28-1, Nishi-Fukushima, Kubiki-mura, Naka Kubiki-gun, Niigata-ken, JAPAN (same for both of the inventors)

(hereinafter referred to as ASSIGNOR), have invented and own a certain invention entitled: "COMPOSITION FOR FORMING POROUS FILM, POROUS FILM AND METHOD FOR FORMING THE SAME, INTERLEVEL INSULATOR FILM, AND SEMICONDUCTOR DEVICE"

for which application for United States Letters Patent identified as \_\_\_\_\_  
\_\_\_\_\_ has been executed on the 5th day of March, 2004, and,

WHEREAS: SHIN-ETSU CHEMICAL CO., LTD., a corporation duly organized under and pursuant to the laws of JAPAN and having its principal place of business at 6-1, Otemachi 2-chome, Chiyoda-ku, Tokyo, JAPAN and MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD., a corporation duly organized under and pursuant to the laws of JAPAN and having its principal place of business at 1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501, JAPAN

(hereinafter referred to as "ASSIGNEE"), has equitable rights in and to this invention and desires to confirm such rights and to acquire all right, title and interest in and to this invention, including any and all United States Letters Patent or similar legal protection to be obtained therefor.

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, ASSIGNOR hereby sells, assigns, and transfers to said ASSIGNEE, its successors and assigns, all right, title and interest in and to said invention, including any and all United States Letters Patent which may be granted therefor and any and all extensions, continuations, divisions, renewals, substitutes or reissues thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property.

ASSIGNOR hereby covenants that no assignment, sale, agreement of encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

ASSIGNOR further covenants and agrees, upon request, to execute any instrument which said ASSIGNEE desires to carry this assignment in effect, and perfect the title transferred hereby, or to file or prosecute any of the above-mentioned United States applications.

And the Commissioner of Patents of the United States is hereby authorized to issue Letters Patent on said above-named application and on any continuation, substitute or division thereof to said ASSIGNEE.

IN TESTIMONY WHEREOF, I/We have hereunto set hand and seal this 5th day of March, 2004

Witnesses:

Jim Galar

Adri Park

ASSIGNOR:

Fujio Yagihashi  
Fujio YAGIHASHI

Yoshitaka Hamada  
Yoshitaka HAMADA

182-625

## ASSIGNMENT

WHEREAS: Hideo NAKAGAWA of 131, Oda-cho, Oumihachiman-shi, Shiga 523-0064 JAPAN and Masaru SASAGO of 1-19-22, Doyama, Hirakata-shi, Osaka 573-0007 JAPAN

(hereinafter referred to as ASSIGNOR), have invented and own a certain invention entitled:

"COMPOSITION FOR FORMING POROUS FILM, POROUS FILM AND METHOD FOR FORMING THE SAME, INTERLEVEL INSULATOR FILM, AND SEMICONDUCTOR DEVICE"

for which application for United States Letters Patent identified as \_\_\_\_\_  
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And the Commissioner of Patents of the United States is hereby authorized to issue Letters Patent on said above-named application and on any continuation, substitute or division thereof to said ASSIGNEE.

IN TESTIMONY WHEREOF, I/We have hereunto set hand and seal this 5th day of March, 2004

Witnesses:

Masayuki Endo  
Shinji Kishimura

ASSIGNOR:

Hideo Nakagawa  
Masaru Sasago  
Hideo NAKAGAWA  
Masaru SASAGO